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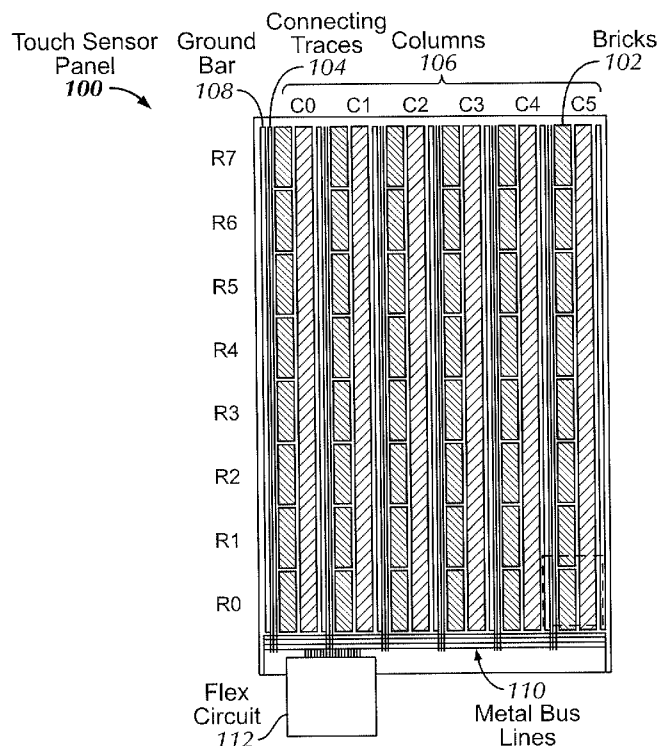


FIG. 1A

(57) Abstract: A touch sensor panel is disclosed having an array of co-planar single-layer touch sensors fabricated on a single side of a substrate. The sense (or drive) lines can be fabricated in a single strip as columnar or zig-zag patterns in a first orientation, and the drive (or sense) lines can be fabricated as rows of polygonal (e.g. brick-shaped or pentagonal) conductive areas in a second orientation. Each sense (or drive) line in the first orientation can be coupled to a separate metal trace in the border area of the touch sensor panel, and each polygonal area in the second orientation can also be coupled to a metal trace in the border area of the touch sensor panel. The metal traces can allow both the row and column lines to be routed to the same edge of the substrate for flex circuit attachment.

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BRICK LAYOUT AND STACKUP FOR A TOUCH SCREEN

Field of the Invention

[0001] This relates generally to input devices for computing systems, and more particularly, to a touch sensor panel capable of being fabricated on a single side of a substrate.

Background of the Invention

[0002] Many types of input devices are presently available for performing operations in a computing system, such as buttons or keys, mice, trackballs, touch sensor panels, joysticks, touch screens and the like. Touch screens, in particular, are becoming increasingly popular because of their ease and versatility of operation as well as their declining price. Touch screens can include a touch sensor panel, which can be a clear panel with a touch-sensitive surface. The touch sensor panel can be positioned in front of a display screen so that the touch-sensitive surface covers the viewable area of the display screen. Touch screens can allow a user to make selections and move a cursor by simply touching the display screen via a finger or stylus. In general, the touch screen can recognize the touch and position of the touch on the display screen, and the computing system can interpret the touch and thereafter perform an action based on the touch event.

[0003] Touch sensor panels can be implemented as an array of pixels formed by multiple drive lines (e.g. rows) crossing over multiple sense lines (e.g. columns), where the drive and sense lines are separated by a dielectric material. In some touch sensor panels, the row and column lines can be formed on different substrates. Such touch sensor panels can be expensive to manufacture, because processing must be performed on two different substrates. In addition, the use of two substrates can result in a thicker device. In other touch sensor panels, the drive and sense lines can be formed on the top

and bottom sides of the same substrate. However, touch sensor panels having row and column lines formed on the bottom and top sides of a single substrate can also be expensive to manufacture, because thin-film processing steps must be performed on both sides of the glass substrate, which requires protective measures for the processed side while the other side is being processed.

Summary of the Invention

[0004] This relates to a touch sensor panel having an array of co-planar single-layer touch sensors fabricated on a single side of a substrate for detecting single or multi-touch events (the touching of one or multiple fingers or other objects upon a touch-sensitive surface at distinct locations at about the same time). The sense (or drive) lines can be fabricated in a single strip as columnar or zig-zag patterns in a first orientation, and the drive (or sense) lines can be fabricated as rows of polygonal (e.g. brick-shaped or pentagonal) conductive areas in a second orientation. Because the drive and sense lines can be formed on the same layer, manufacturing costs can be reduced and the touch sensor panel can be made thinner. Each sense (or drive) line in the first orientation can be coupled to a separate metal trace in the border area of the touch sensor panel, and each polygonal area in the second orientation can also be coupled to a metal trace in the border area of the touch sensor panel. The metal traces in the border areas can be formed on the same side of the substrate as the drive and sense lines. The metal traces can allow both the row and column lines to be routed to the same edge of the substrate so that a small flex circuit can be bonded to a small area on only one side of the substrate.

[0005] In some embodiments, the connecting traces are routed along only one side of the bricks (a so-called "single escape" configuration). To couple the bricks in a particular row together, connecting traces, which are also formed from a conductive material, can be routed from the bricks along one side of the bricks in a single escape configuration to a particular bus line. Connections for each bus line and for the columns can be brought off the touch sensor panel through a flex circuit.

[0006] Because some bus lines can have much shorter connecting traces to the bricks as compared to other bus lines, the impedance and capacitance of certain bus lines can be much greater than that of other bus lines. Because of this imbalance, touch measurements for a given amount of touch may not be equalized across the touch sensor panel. Therefore, in some embodiments of the invention, the bricks coupled to a particular bus line can be interleaved so that each bus line sees a more uniform average impedance and capacitance, which can help equalize touch measurements across the touch sensor panel.

[0007] Interleaving can additionally provide increased power uniformity. Without interleaving, some drivers can have a small capacitive load, while others can have a large capacitive load. To ensure that the largest load can be properly driven, all drivers may be designed to drive the largest capacitive load, resulting in higher current requirements for all drivers, even those not driven with a large load. However, with interleaving, each driver can have a more moderate and roughly equivalent capacitive load, and the drivers need only be designed to drive the moderate capacitive load.

[0008] In some embodiments, the connecting traces are alternately routed along both sides of the bricks (a so-called "double escape" configuration). To couple the bricks in a particular row together, connecting traces, which are also formed from a conductive material, can be routed from the bricks along alternating sides of the bricks in a double escape configuration to a particular lower bus line or an upper bus line (although it should be understood that in other embodiments, only a single group of bus lines at either the top or bottom may be employed). The lower bus lines and upper bus lines, as well as connecting traces for columns, can be routed along the border areas and brought off the touch sensor panel through a flex circuit.

[0009] For the very longest routing traces, there can be on the order of about 6 pF of C_{sig} transferred from the connecting traces to nearby sense lines, which can reduce the dynamic range budget and can make calibration difficult. Accordingly, a zig-zag double interpolated touch sensor panel can further reduce the stray capacitance between the connecting traces and the sense lines. Polygonal areas representing the drive (or sense) lines generally pentagonal in shape and staggered in orientation can be

formed, with some of the polygonal areas near the end of the panel being cut-off pentagons. The sense (or drive) lines are zig-zag shaped. All connecting traces are routed in channels between pentagons. Because the connecting traces do not run alongside any sense (or drive) lines, but instead run between pentagons, the stray
5 capacitance between the connecting traces and the sense (or drive) lines is minimized, and spatial cross-coupling is also minimized.

Brief Description of the Drawings

[0010] FIG. 1A illustrates an exemplary touch sensor panel including columns, rows of bricks, and connecting traces routed along only one side of the bricks according
10 to embodiments of the invention.

[0011] FIG. 1B illustrates a close-up view of a portion of the exemplary touch sensor panel of FIG. 1A, showing bricks routed to bus lines using connecting traces in a single escape configuration according to embodiments of the invention.

[0012] FIG. 1C illustrates a portion of the exemplary touch sensor panel of FIG.
15 1A, including bricks associated with columns C0 and C1 and connecting traces coupling the bricks to the bus lines according to embodiments of the invention.

[0013] FIG. 2A illustrates a side view of a portion of an exemplary touch sensor panel showing the connections between connecting traces and bus lines according to embodiments of the invention.

20 [0014] FIG. 2B illustrates a top view of a portion of the exemplary bus lines of FIG. 2A according to embodiments of the invention.

[0015] FIG. 3 illustrates a portion of an exemplary touch sensor panel including rows of bricks whose connecting traces are interleaved according to embodiments of the invention.

25 [0016] FIG. 4A illustrates an exemplary touch sensor panel including columns, rows of bricks, and connecting traces routed along both sides of the bricks according to embodiments of the invention.

[0017] FIG. 4B illustrates a close-up view of a portion of the exemplary touch sensor panel of FIG. 4A, showing bricks routed to lower bus lines using connecting traces in a double escape configuration according to embodiments of the invention.

5 [0018] FIGs. 5A and 5B illustrate top and side views of the effect of an exemplary ground guard on electric field lines emanating from a polygonal area of conductive material according to embodiments of the invention.

[0019] FIGs. 5C and 5D illustrate top and side views of the effect of an exemplary ground guard on electric field lines emanating from a connecting trace according to embodiments of the invention.

10 [0020] FIGs. 5E and 5F illustrate top and side views of the effect of an exemplary ground guard on electric field lines emanating from a polygonal conductive area and separated from a sense line by connecting traces according to embodiments of the invention.

15 [0021] FIG. 6 illustrates a portion of an exemplary zig-zag double interpolated touch sensor panel that can further reduce the stray capacitance between the connecting traces and the columns according to embodiments of the invention.

[0022] FIG. 7 illustrates an exemplary computing system operable with the touch sensor panel according to embodiments of this invention.

20 [0023] FIG. 8A illustrates an exemplary mobile telephone that can include the touch sensor panel according to embodiments of the invention.

[0024] FIG. 8B illustrates an exemplary media player that can include the touch sensor panel according to embodiments of the invention.

Detailed Description of the Preferred Embodiments

25 [0025] In the following description of preferred embodiments, reference is made to the accompanying drawings which form a part hereof, and in which it is shown by way of illustration specific embodiments in which the invention can be practiced. It is

to be understood that other embodiments can be used and structural changes can be made without departing from the scope of the embodiments of this invention.

5 **[0026]** This relates to a touch sensor panel having an array of co-planar single-layer touch sensors fabricated on a single side of a substrate for detecting single or multi-touch events (the touching of one or multiple fingers or other objects upon a touch-sensitive surface at distinct locations at about the same time). In mutual capacitance embodiments, each sensor or pixel can be the result of interactions between drive and sense lines. The sense (or drive) lines can be fabricated in a single strip as columnar or zig-zag patterns in a first orientation, and the drive (or sense) lines can be fabricated as rows of polygonal (e.g. brick-shaped or pentagonal) conductive areas in a second orientation. Because the drive and sense lines can be formed on the same layer, manufacturing costs can be reduced and the touch sensor panel can be made thinner. Each sense (or drive) line in the first orientation can be coupled to a separate metal trace in the border area of the touch sensor panel, and each polygonal area in the second orientation can also be coupled to a metal trace in the border area of the touch sensor panel. The metal traces in the border areas can be formed on the same side of the substrate as the drive and sense lines. The metal traces can allow both the row and column lines to be routed to the same edge of the substrate so that a small flex circuit can be bonded to a small area on only one side of the substrate.

20 **[0027]** Although some embodiments of this invention may be described and illustrated herein primarily in terms of mutual capacitance multi-touch sensor panels, it should be understood that embodiments of this invention are not so limited, but can be additionally applicable to self-capacitance sensor panels and single-touch sensor panels. Furthermore, although the touch sensors in the sensor panel may be described and illustrated herein in terms of generally orthogonal arrangements of drive (or sense) lines formed as rows of rectangular bricks or pentagonal shapes, and sense (or drive) lines formed as columnar or zig-zag patterns, embodiments of this invention are not so limited, but can be additionally applicable to polygonal areas of other shapes and lines formed in other patterns.

[0028] FIG. 1A illustrates exemplary touch sensor panel 100 including sense (or drive) lines (C0-C5) formed as columns 106 and rows of polygonal areas (bricks) 102, where each row of bricks forms a separate drive (or sense) line (R0-R7) according to embodiments of the invention. In the example of FIG. 1A, connecting traces 104 are routed along only one side of the bricks (a so-called “single escape” configuration). Although a touch sensor panel 100 having six columns and eight rows is shown, it should be understood that any number of columns and rows can be employed. Columns 106 and bricks 102 of FIG. 1A can be formed in a co-planar single layer of conductive material.

10 [0029] To couple bricks 102 in a particular row together, connecting traces 104, which are also formed from a conductive material, can be routed from the bricks along one side of the bricks in a single escape configuration to a particular bus line 110. Ground isolation bars 108, which are formed from conductive material, can be formed between connecting traces 104 and adjacent columns 106 to reduce the capacitive
15 coupling between the connecting traces and the columns. Connections for each bus line 110 and for columns 106 can be brought off touch sensor panel 100 through flex circuit 112. In touch screen embodiments, the sense lines, drive lines, connecting traces and ground isolation bars can be formed from a substantially transparent material such as Indium Tin Oxide (ITO), although other materials can also be used. The ITO layer can
20 be formed on a single layer on either the back of a coverglass or a separate substrate.

[0030] FIG. 1B illustrates a close-up view of a portion of the exemplary touch sensor panel 100 of FIG. 1A, showing how bricks 102 can be routed to bus lines 110 using connecting traces 104 in a single escape configuration according to embodiments of the invention. In FIG. 1B, the longer connecting traces 104 (e.g. trace R7) can be
25 wider than the shorter connecting traces (e.g. trace R2) to equalize the overall resistivity of the traces and to minimize the overall capacitive loads seen by the drive circuitry.

[0031] FIG. 1C illustrates a portion of exemplary touch sensor panel 100 of FIG. 1A including bricks 102 associated with columns C0 and C1 and connecting traces 104 (illustrated symbolically as thin lines) coupling the bricks to bus lines 110
30 according to embodiments of the invention. In the example of FIG. 1B, which is drawn

in a symbolic manner and not to scale for purposes of illustration only, bus line B0 is coupled to brick R0C0 (the closest brick to B0 adjacent to column C0) and R0C1 (the closest brick to B0 adjacent to column C1). Bus line B1 is coupled to brick R1C0 (the next closest brick to B0 adjacent to column C0) and R1C1 (the next closest brick to B0 adjacent to column C1). The pattern repeats for the other bus lines such that bus line B7 is coupled to brick R7C0 (the farthest brick from B0 adjacent to column C0) and R7C1 (the farthest brick from B0 adjacent to column C1).

[0032] FIG. 2A illustrates a side view of a portion of exemplary touch sensor panel 200 showing the coupling between connecting traces 204 and bus lines 210 according to embodiments of the invention. In FIG. 2A, bus lines 210 and pads 218 (e.g. metal having a resistance of 1 ohm per square maximum) can be formed on substrate 220 (e.g. glass having a thickness of 500 microns +/- 50 microns). Insulating layer 214 (e.g. organic polymer having a thickness of 3 microns minimum) can then be formed over bus lines 210 and pads 218 and patterned to create vias 216. Connecting traces 204 can then be formed over insulating layer 214 and into vias 216 to make connections between the traces and bus lines 210. In addition, the same conductive material used to form connecting traces 204 can also be partially formed over pads 218 at location 222 to protect the pads. On the back side of substrate 220, conductive shield layer 224 (e.g. ITO having a thickness of 50 microns +/- 10 microns) can be formed over substrate 220 to shield the sense lines (not shown in FIG. 2A). Anti-reflective (AR) film 226 having a particular thickness (e.g. 75 microns +/- 15 microns) can then be affixed to shield layer 224 using an adhesive such as a 25 micron layer of PSA. Flex circuit 212 can be attached to both the top and bottom of touch sensor panel 200 using an adhesive 228 (e.g. anisotropic conductive film (ACF)) capable of forming conductive bonds. Finally, touch sensor panel 200 can be bonded to cover material 230 (e.g. glass having a thickness of 800 to 1100 microns) using adhesive 232 (e.g. low-acid pressure sensitive adhesive (PSA) having a thickness of 150 microns +/- 25 microns).

[0033] FIG. 2B illustrates a top view of a portion of the exemplary bus lines 210 of FIG. 2A according to embodiments of the invention. Note that in the example of

FIG. 2B, the top bus line is wider (e.g. 100 microns) at the point at which via 216 provides for a connection between bus line 210 and a connecting trace.

[0034] Referring again to the example of FIG. 1C, because bus line B0 has much shorter connecting traces 104 to bricks R0C0 and R0C1 as compared to bus line B7 (and its connecting traces to bricks R7C0 and R7C1), the impedance and capacitance of bus line B7 can be much greater than that of bus line B0. Because of this imbalance, touch measurements for a given amount of touch may not be equalized across the touch sensor panel. Therefore, in some embodiments of the invention, the bricks coupled to a particular bus line can be interleaved so that each bus line sees a more uniform average impedance and capacitance, which can help equalize touch measurements across the touch sensor panel.

[0035] FIG. 3 illustrates a portion of exemplary touch sensor panel 300 including drive (or sense) lines formed as bricks 302 whose connecting traces 304 are interleaved according to embodiments of the invention. In the example of FIG. 3, which is drawn in a symbolic manner and not to scale for purposes of clarity, bus line B0 is coupled to brick R0C0 (the closest brick to B0 adjacent to column C0) and R7C1 (the farthest brick from B0 adjacent to column C1). Bus line B1 is coupled to brick R1C0 (the next closest brick to B0 adjacent to column C0) and R6C1 (the next farthest brick from B0 adjacent to column C1). This coupling pattern repeats for the other bus lines, as evidenced by bus line B7 coupled to brick R7C0 (the farthest brick from B0 adjacent to column C0) and R0C1 (the closest brick to B0 adjacent to column C1). By interleaving the bricks coupled to any particular bus line as described above, each bus line sees a more uniform average impedance and capacitance, which can help equalize touch measurements across the touch sensor panel. However, it should be understood that with this arrangement, for a given bus line, the location of the bricks being stimulated can vary greatly. Nevertheless, post-processing of the resultant touch image can identify the actual touch locations.

[0036] Interleaving can additionally provide increased power uniformity. Without interleaving, some drivers can have a small capacitive load, while others can have a large capacitive load. To ensure that the largest load can be properly driven, all

drivers may be designed to drive the largest capacitive load, resulting in higher current requirements for all drivers, even those not driven with a large load. However, with interleaving, each driver can have a more moderate and roughly equivalent capacitive load, and the drivers need only be designed to drive the moderate capacitive load.

5 **[0037]** FIG. 4A illustrates exemplary touch sensor panel 400 including sense (or drive) lines formed as columns 406, drive (or sense) lines formed as rows of bricks 402, and connecting traces 404 (illustrated symbolically as thin lines) routed along both sides of the bricks (a so-called “double escape” configuration) according to embodiments of the invention. In the example of FIG. 4A, sense (or drive) lines (C0-C3) can be formed
10 as columns 406 and drive (or sense) lines (R0-R7) can be formed as rows of bricks 402, where each row of bricks forms a separate drive (or sense) line. Although a touch sensor panel 400 having four columns and eight rows is shown, it should be understood that any number of columns and rows can be employed. Columns 406 and bricks 402 of FIG. 4A can be formed in a co-planar single layer of conductive material.

15 **[0038]** To couple bricks 402 in a particular row together, connecting traces 404, which are also formed from a conductive material, can be routed from the bricks along alternating sides of the bricks in a double escape configuration to a particular lower bus line 410 or upper bus line 414 (although it should be understood that in other
20 embodiments, only a single group of bus lines at either the top or bottom may be employed). Ground guards 416, which are formed from conductive material, can be formed between connecting traces 404 and adjacent columns 406. Lower bus lines 410 and upper bus lines 414, as well as connecting traces for columns 406, can be routed along the border areas and brought off touch sensor panel 400 through a flex circuit.

25 **[0039]** FIG. 4B illustrates a close-up view of a portion of the exemplary touch sensor panel 400 of FIG. 4A, showing how bricks 402 can be routed to lower bus lines 410 using connecting traces 404 in a double escape configuration according to
30 embodiments of the invention. In the example of FIG. 4B, connecting trace 404-R0-E can be routed directly to lower bus lines 410, connecting trace 404-R1-E can be routed along the right side of brick R0-E, connecting trace 404-R2-E can be routed along the left side of bricks R0-E and R1-E, and connecting trace 404-R3-E can be routed along

the right side of bricks R0-E, R1-E and R2-E (not shown) in the double escape configuration.

[0040] In the mutual capacitance double escape embodiment of FIG. 4B, each pixel can be characterized by the mutual capacitance between a column and two adjacent bricks. For example, the pixel or sensor for R0-C3 can be formed by mutual capacitance 418 between brick R0-D and C3, and also mutual capacitance 420 between brick R0-E and C3.

[0041] As mentioned above, an optional ground guard can be formed around each column in FIGs. 4A and 4B, and can also be formed around each column in FIGs. 1A, 1B, 1C and 3. In one embodiment, the columns can be around 1000 microns wide, and the ground guard can be around 250 microns wide. One benefit of using a ground guard is improving the touch event detection capabilities of the touch sensor panel.

[0042] FIGs. 5A and 5B illustrate top and side views of the effect of exemplary ground guard 500 on polygonal area of conductive material 502 according to embodiments of the invention.

[0043] FIG. 5A illustrates an example without a ground guard. When either polygonal area of conductive material 502 or column 504 is driven by a stimulation signal, fringing electric field lines 506 appear between the polygonal area 502 and column 504. As the side view illustrates, some electric field lines can temporarily exit cover glass 508 in the process. Electric field lines 506 include near field lines 510, which generally do not exit cover glass 508 and are therefore largely unaffected by a finger appearing on or in proximity to the cover glass. For example, near field lines 510 may generate a stray capacitance, C_{sig} , of about 2.4 pF, but the change in the stray capacitance during a touch event, ΔC_{sig} , may be only about 0.05 pf, which is a small change of about 2%. Electric field lines 506 also include far field lines 512, some of which can temporarily exit cover glass 506 and can be blocked by a finger. In contrast to near field lines 510, far field lines 512 may generate C_{sig} of about 0.6 pF, but experience a change in the stray capacitance during a touch event, ΔC_{sig} , of about 0.3

pF, which is a much larger change of about 50%. This large change represents a better signal-to-noise ratio (SNR) and improved touch event detection.

[0044] However, because both near and far field lines 510 and 512 are present when either polygonal conductive area 502 or column 504 is being stimulated, the total Csig being generated in the example above is about 3.0 pF and the total change in the stray capacitance ΔC_{sig} during a touch event is about 0.35 pf, which represents only about a 10% change. To maximize the percentage change in stray capacitance during a touch event, it is desirable to minimize the amount of mutual capacitance that is unaffected by a touch event (i.e. near field lines 510), and instead rely as much as possible on the mutual capacitance that is changed by the touch event (i.e. far field lines 512).

[0045] FIG. 5B illustrates an example with ground guard 500. As FIG. 5B illustrates, ground guard 500 can reduce the undesirable mutual capacitance between the drive and sense lines by shunting most near field lines 510 directly to ground instead of allowing them to couple to sense line 504, leaving mostly far field lines 512 affected by touch events. With mostly far field lines 512 affecting the mutual capacitance value, the change in capacitance during a touch event can approach 50% as discussed above, which represents an improved SNR.

[0046] FIGs. 5C and 5D illustrate top and side views of the effect of exemplary ground guard 500 on connecting trace 514 according to embodiments of the invention. FIG. 5C illustrates an example without a ground guard. Because connecting trace 514 can be coupled to a polygonal conductive area, it too can be driven with a stimulation signal. Without a ground guard, as illustrated in FIG. 5C, near field lines 510 can couple onto adjacent sense line 504, causing unintended changes in capacitance on the sense line. However, with a ground guard 500 in place as shown in FIG. 5D, near field lines 510 can be shunted to the ground guard instead of sense line 504, decreasing the unintended change in capacitance on the sense line.

[0047] FIGs. 5E and 5F illustrate top and side views of the effect of exemplary ground guard 500 on polygonal conductive area 502 separated from sense line 504 by

connecting traces 514 according to embodiments of the invention. Without a ground guard, as illustrated in FIG. 5E, near field lines 510 can couple onto sense line 504, reducing the percentage change in capacitance on the sense line when a touch event occurs. However, with a ground guard 500 in place as shown in FIG. 5F, near field lines 510 can be shunted to the ground guard instead of sense line 504, leaving mostly far field lines 512 affected by touch events, increasing the percentage change in capacitance on the sense line when a touch event occurs.

[0048] Referring again to FIG. 1A, the previously mentioned ground isolation bars can minimize the amount of stray capacitance, C_{sig} , between the connecting traces and the sense lines. Nevertheless, for the very longest routing traces, there can still be on the order of about 6 pF of C_{sig} transferred from the connecting traces to the sense lines, which can reduce the dynamic range budget and can make calibration difficult. Because the stray capacitance from the connecting traces to sense lines is somewhat affected by a touch event, it can cause spatial cross-coupling in which a touch event in one region of the touch sensor panel additionally causes a decrease in the stray capacitance and an apparent (but false) touch event in remote areas of the panel.

[0049] FIG. 6 illustrates a portion of exemplary zig-zag double interpolated touch sensor panel 600 that can further reduce the stray capacitance between the connecting traces and the sense lines according to embodiments of the invention. In the example of FIG. 6, polygonal areas 602 representing the drive (or sense) lines are generally pentagonal in shape and staggered in orientation, with some of the polygonal areas near the end of the panel being cut-off pentagons. Sense (or drive) lines 604 are zig-zag shaped, with ground guards 606 between the sense (or drive) lines and pentagons 602. All connecting traces 608 are routed in channels 610 between pentagons 602. In mutual capacitance embodiments, each pixel or sensor is characterized by electric field lines 616 formed between a pentagon and an adjacent sense (or drive) line 604. Because connecting traces 608 do not run alongside any sense (or drive) lines 604, but instead run between pentagons 602, the stray capacitance between connecting traces 608 and sense (or drive) lines 604 is minimized, and spatial cross-coupling is also minimized. Previously, the distance between connecting traces

608 and sense (or drive) lines 604 was only the width of ground guard 606, but in the embodiment of FIG. 6, the distance is the width of the ground guard plus the width of pentagon 602 (which varies along the length of its shape).

[0050] As the example of FIG. 6 indicates, the pentagons for row R14 at an end of the touch sensor panel can be truncated. Accordingly, the calculated centroids of touch 612 for R14 can be offset in the y-direction from their true position. In addition, the calculated centroids of touch for any two adjacent rows will be staggered (offset from each other) in the x-direction by an offset distance. However, this misalignment can be de-warped in a software algorithm to re-map the pixels and remove the distortion.

[0051] Although embodiments of the invention have been primarily described herein in terms of mutual capacitance touch sensor panels, it should be understood that embodiments of the invention are also applicable to self-capacitance touch sensor panels. In such an embodiment, a reference ground plane can be formed either on the back side of the substrate, or on the same side of the substrate as the polygonal areas and sense lines but separated from the polygonal areas and sense lines by a dielectric, or on a separate substrate. In a self-capacitance touch sensor panel, each pixel or sensor has a self-capacitance to the reference ground that can be changed due to the presence of a finger.

[0052] FIG. 7 illustrates exemplary computing system 700 that can include one or more of the embodiments of the invention described above. Computing system 700 can include one or more panel processors 702 and peripherals 704, and panel subsystem 706. Peripherals 704 can include, but are not limited to, random access memory (RAM) or other types of memory or storage, watchdog timers and the like. Panel subsystem 706 can include, but is not limited to, one or more sense channels 708, channel scan logic 710 and driver logic 714. Channel scan logic 710 can access RAM 712, autonomously read data from the sense channels and provide control for the sense channels. In addition, channel scan logic 710 can control driver logic 714 to generate stimulation signals 716 at various frequencies and phases that can be selectively applied to drive lines of touch sensor panel 724. In some embodiments, panel subsystem 706,

panel processor 702 and peripherals 704 can be integrated into a single application specific integrated circuit (ASIC).

5 [0053] Touch sensor panel 724 can include a capacitive sensing medium having a plurality of drive lines and a plurality of sense lines, although other sensing media can also be used. In mutual capacitance embodiments, each intersection of drive and sense lines can represent a capacitive sensing node and can be viewed as picture element (pixel) 726, which can be particularly useful when touch sensor panel 724 is viewed as capturing an "image" of touch. In other words, after panel subsystem 706 has determined whether a touch event has been detected at each touch sensor in the touch sensor panel, the pattern of touch sensors in the multi-touch panel at which a touch event occurred can be viewed as an "image" of touch (e.g. a pattern of fingers touching the panel. Each sense line of touch sensor panel 724 can be coupled to a sense channel 708 (also referred to herein as an event detection and demodulation circuit) in panel subsystem 706.

15 [0054] Computing system 700 can also include host processor 728 for receiving outputs from panel processor 702 and performing actions based on the outputs that can include, but are not limited to, moving an object such as a cursor or pointer, scrolling or panning, adjusting control settings, opening a file or document, viewing a menu, making a selection, executing instructions, operating a peripheral device coupled to the host device, answering a telephone call, placing a telephone call, terminating a telephone call, changing the volume or audio settings, storing information related to telephone communications such as addresses, frequently dialed numbers, received calls, missed calls, logging onto a computer or a computer network, permitting authorized individuals access to restricted areas of the computer or computer network, loading a user profile associated with a user's preferred arrangement of the computer desktop, 25 permitting access to web content, launching a particular program, encrypting or decoding a message, and/or the like. Host processor 728 can also perform additional functions that may not be related to panel processing, and can be coupled to program storage 732 and display device 730 such as an LCD display for providing a UI to a user

of the device. Display device 730 together with touch sensor panel 724, when located partially or entirely under the touch sensor panel, can form touch screen 718.

[0055] Note that one or more of the functions described above can be performed by firmware stored in memory (e.g. one of the peripherals 704 in FIG. 7) and executed by panel processor 702, or stored in program storage 732 and executed by host processor 728. The firmware can also be stored and/or transported within any computer-readable medium for use by or in connection with an instruction execution system, apparatus, or device, such as a computer-based system, processor-containing system, or other system that can fetch the instructions from the instruction execution system, apparatus, or device and execute the instructions. In the context of this document, a "computer-readable medium" can be any medium that can contain or store the program for use by or in connection with the instruction execution system, apparatus, or device. The computer readable medium can include, but is not limited to, an electronic, magnetic, optical, electromagnetic, infrared, or semiconductor system, apparatus or device, a portable computer diskette (magnetic), a random access memory (RAM) (magnetic), a read-only memory (ROM) (magnetic), an erasable programmable read-only memory (EPROM) (magnetic), a portable optical disc such as a CD, CD-R, CD-RW, DVD, DVD-R, or DVD-RW, or flash memory such as compact flash cards, secured digital cards, USB memory devices, memory sticks, and the like.

[0056] The firmware can also be propagated within any transport medium for use by or in connection with an instruction execution system, apparatus, or device, such as a computer-based system, processor-containing system, or other system that can fetch the instructions from the instruction execution system, apparatus, or device and execute the instructions. In the context of this document, a "transport medium" can be any medium that can communicate, propagate or transport the program for use by or in connection with the instruction execution system, apparatus, or device. The transport readable medium can include, but is not limited to, an electronic, magnetic, optical, electromagnetic or infrared wired or wireless propagation medium.

[0057] FIG. 8A illustrates exemplary mobile telephone 836 that can include touch sensor panel 824 and display device 830, the touch sensor panel having rows and columns formed as described above according to embodiments of the invention.

5 [0058] FIG. 8B illustrates exemplary digital media player 840 that can include touch sensor panel 824 and display device 830, the touch sensor panel having rows and columns formed as described above according to embodiments of the invention.

[0059] The mobile telephone and media player of FIGs. 8A and 8B can advantageously benefit from the touch sensor panel described above because the touch sensor panel can enable these devices to be more touch sensitive, thinner and less
10 expensive, which are important consumer factors that can have a significant effect on consumer desirability and commercial success.

[0060] Although embodiments of this invention have been fully described with reference to the accompanying drawings, it is to be noted that various changes and modifications will become apparent to those skilled in the art. Such changes and
15 modifications are to be understood as being included within the scope of embodiments of this invention as defined by the appended claims.

WHAT IS CLAIMED IS:

1. A touch sensor panel, comprising:
a plurality of first lines formed on a single layer and supported on one side of a substrate;
5 a plurality of polygonal areas formed on the same layer as the plurality of first lines; and
a plurality of connecting traces routed adjacent to the polygonal areas and formed on the same layer as the plurality of first lines, each connecting trace coupled to a different polygonal area;
10 wherein the plurality of first lines and the plurality of polygonal areas form an array of capacitive sensors.
2. The touch sensor panel of claim 1, wherein the connecting traces coupled to successive polygonal areas in a first orientation are alternately routed along both sides of the polygonal areas.
- 15 3. The touch sensor panel of claim 1, wherein the plurality of connecting traces are routed along one side of the polygonal areas.
4. The touch sensor panel of claim 1, further comprising a plurality of bus lines formed along at least one edge of the substrate on the same side of the substrate as the plurality of first lines, each connecting trace coupled to one of the bus lines.
- 20 5. The touch sensor panel of claim 1, wherein the plurality of first lines are zig-zag-shaped.
6. The touch sensor panel of claim 1, wherein a majority of the plurality of polygonal areas are pentagonal.

7. The touch sensor panel of claim 1, the plurality of connecting traces routed between the polygonal areas.

8. The touch sensor panel of claim 1, wherein the plurality of polygonal areas are brick-shaped.

5 9. The touch sensor panel of claim 4, the plurality of first lines representing a plurality of sense lines in a first orientation and the plurality of polygonal areas representing a plurality of drive lines in a second orientation.

10 10. The touch sensor panel of claim 9, the plurality of polygonal areas formed adjacent to the sense lines, each polygonal area and adjacent sense line forming a sensor of the touch sensor panel.

11. The touch sensor panel of claim 9, each polygonal area in the same drive line coupled to the same bus line.

15 12. The touch sensor panel of claim 9, wherein each bus line is coupled to polygonal areas in at least two different drive lines to substantially equalize a capacitance seen on the bus lines.

13. The touch sensor panel of claim 1, further comprising a reference ground plane formed on a different layer from the layer of the plurality of sense lines and polygonal areas, the reference ground plane, sense lines and polygonal areas forming a self-capacitance touch sensor panel.

20 14. The touch sensor panel of claim 1, the touch sensor panel integrated within a computing system.

15. The touch sensor panel of claim 14, the computing system integrated within a mobile telephone.

16. The touch sensor panel of claim 14, the computing system integrated within a media player.

17. A method for fabricating a touch sensor panel, comprising:
forming a plurality of first lines and second lines on a single layer on one
5 side of a substrate, each first line formed as a single continuous strip in a first
orientation, and each second line formed as a plurality of discrete polygonal areas in a
second orientation; and
coupling each of the first lines and discrete polygonal areas to a plurality
of bus lines via connecting traces, the bus lines formed along at least one edge of the
10 substrate on the same side of the substrate as the plurality of first lines, and the
connecting traces routed adjacent to the polygonal areas and formed on the same layer
as the plurality of first lines;
wherein the plurality of first lines and the plurality of second lines form
an array of capacitive sensors on the touch sensor panel.

18. The method of claim 17, further comprising routing the connecting
15 traces coupled to successive second lines along alternating sides of the polygonal areas.

19. The method of claim 17, further comprising routing the plurality of
connecting traces along one side of the polygonal areas.

20. The method of claim 17, further comprising forming each of the plurality
20 of first lines in a zig-zag shape.

21. The method of claim 17, further comprising forming a majority of the
plurality of polygonal areas in a pentagonal shape.

22. The method of claim 17, further comprising routing the plurality of
connecting traces between the polygonal areas.

23. The method of claim 17, further comprising forming the plurality of polygonal areas into brick-shaped areas.

24. The method of claim 17, the plurality of first lines representing a plurality of sense lines and the plurality of second lines representing a plurality of drive
5 lines.

25. The method of claim 24, further comprising forming the plurality of polygonal areas adjacent to the sense lines, each polygonal area and adjacent sense line forming a sensor of the touch sensor panel.

26. The method of claim 24, further comprising coupling each polygonal
10 area in the same drive line to the same bus line.

27. The method of claim 24, further comprising coupling each bus line to polygonal areas in at least two different drive lines to substantially equalize a capacitance seen on the bus lines.

28. The method of claim 17, further comprising forming a reference ground
15 plane on a different layer from the layer of the plurality of sense lines and polygonal areas, the reference ground plane, sense lines and polygonal areas forming a self-capacitance touch sensor panel.

29. A handheld electronic device including a touch sensor panel, the touch sensor panel comprising:

a plurality of first lines formed on a single layer and supported on one side of a substrate;

5 a plurality of polygonal areas formed on the same layer as the plurality of first lines; and

a plurality of connecting traces routed adjacent to the polygonal areas and formed on the same layer as the plurality of first lines, each connecting trace coupled to a different polygonal area;

10 wherein the plurality of first lines and the plurality of polygonal areas form an array of capacitive sensors.

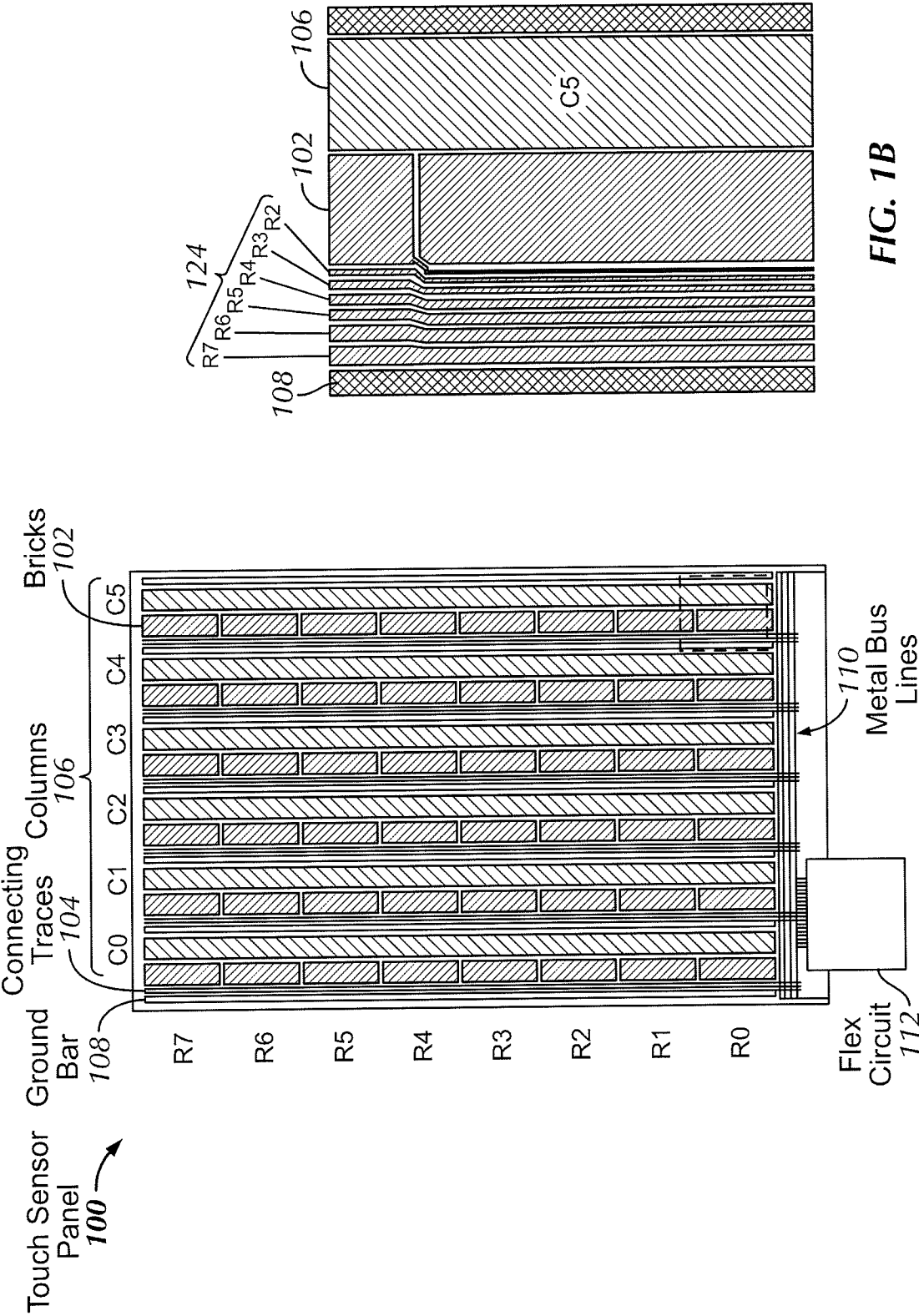


FIG. 1B

FIG. 1A

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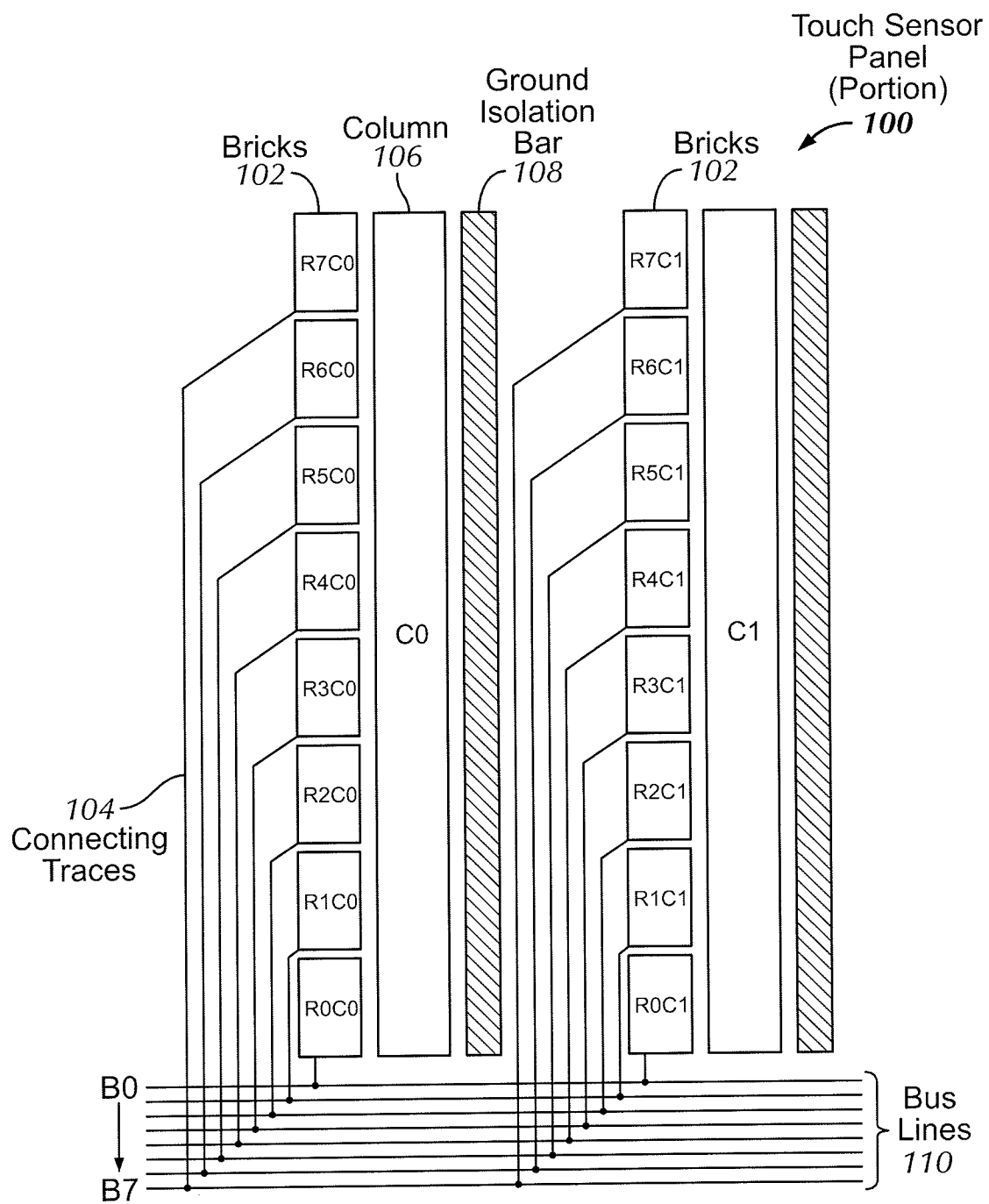


FIG. 1C

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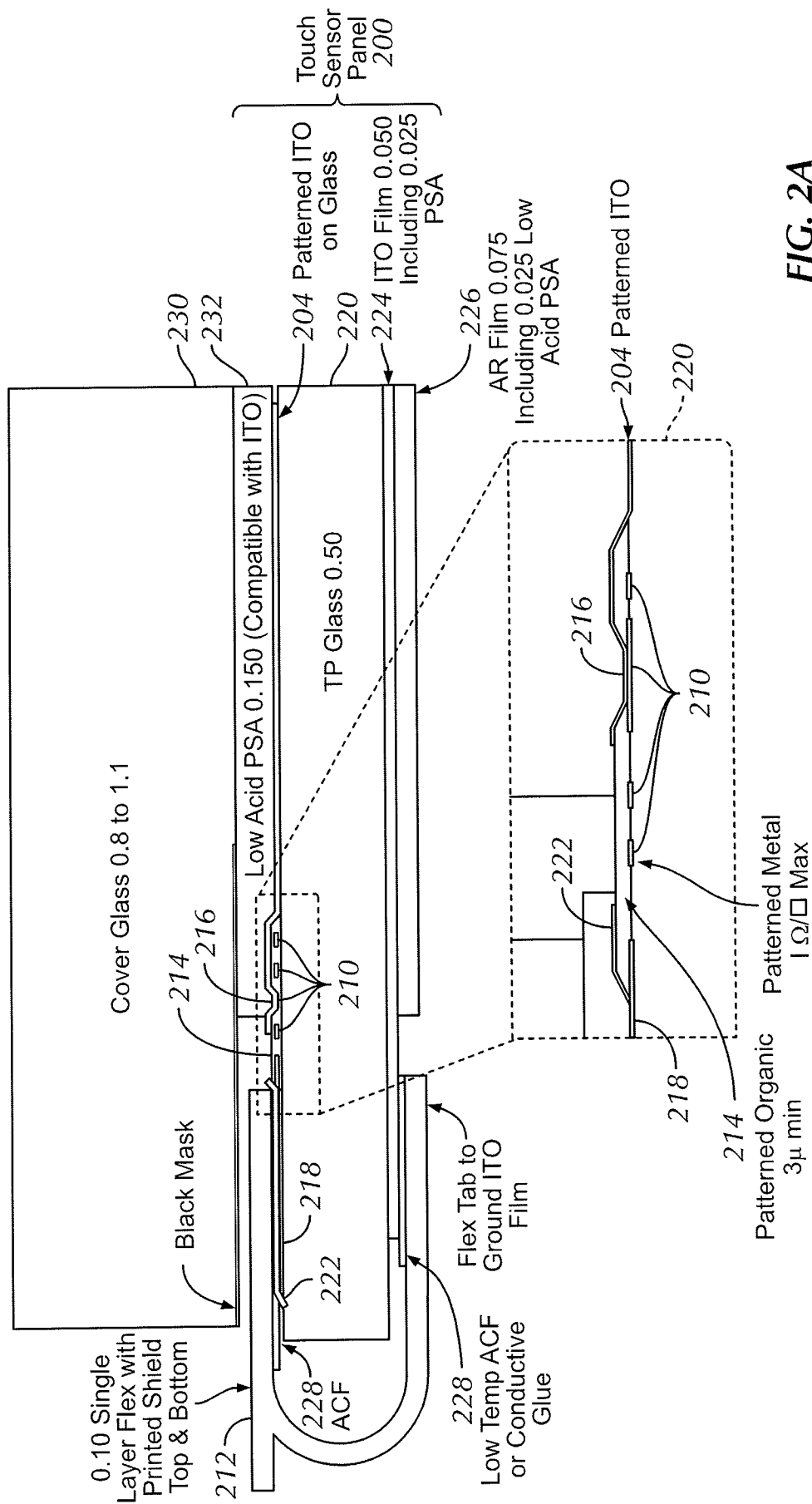


FIG. 2A

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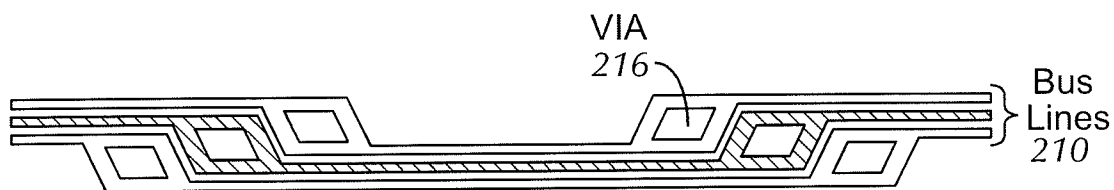


FIG. 2B

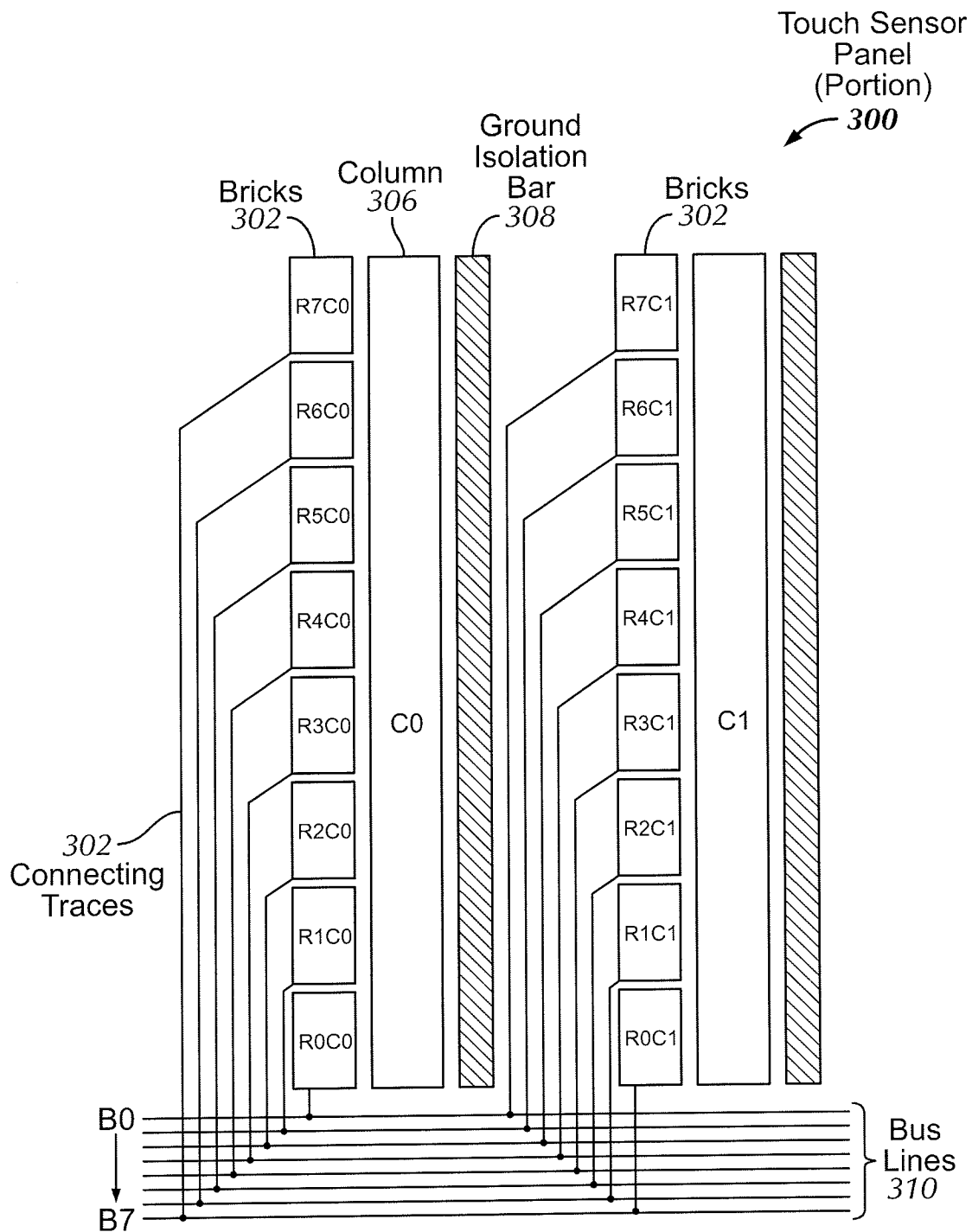


FIG. 3

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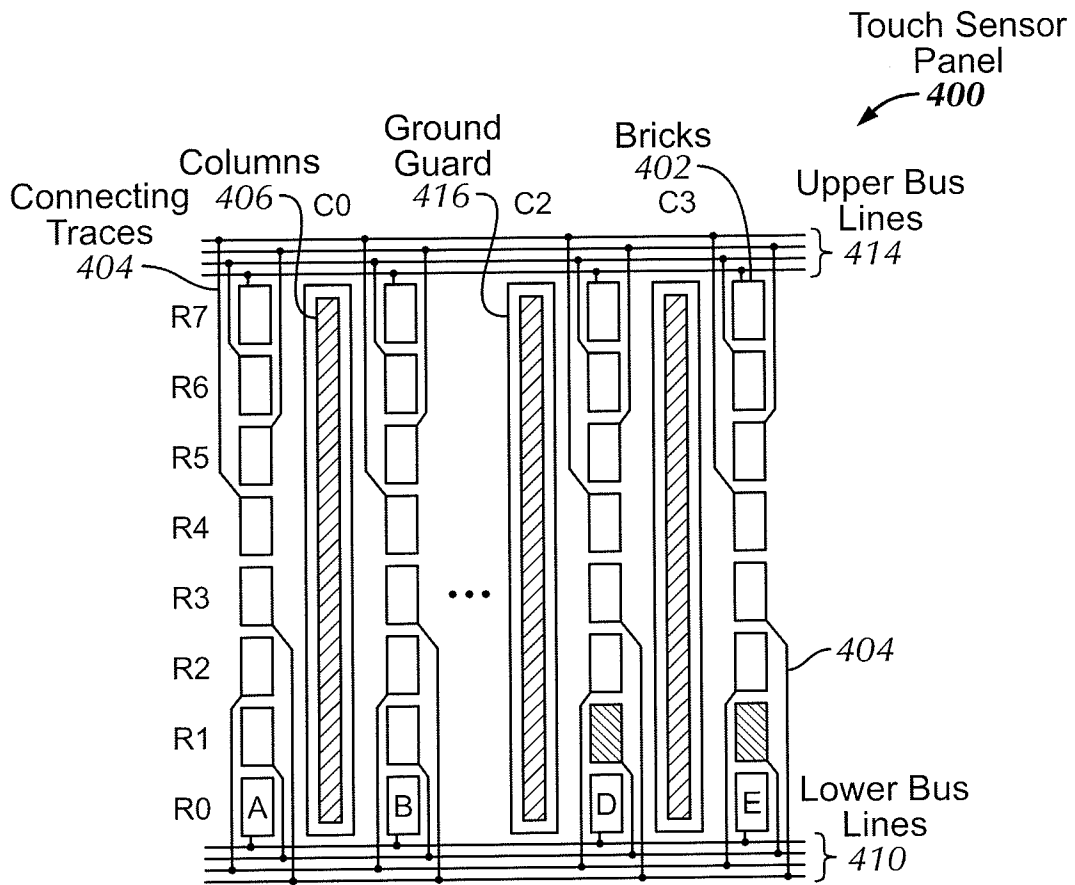


FIG. 4A

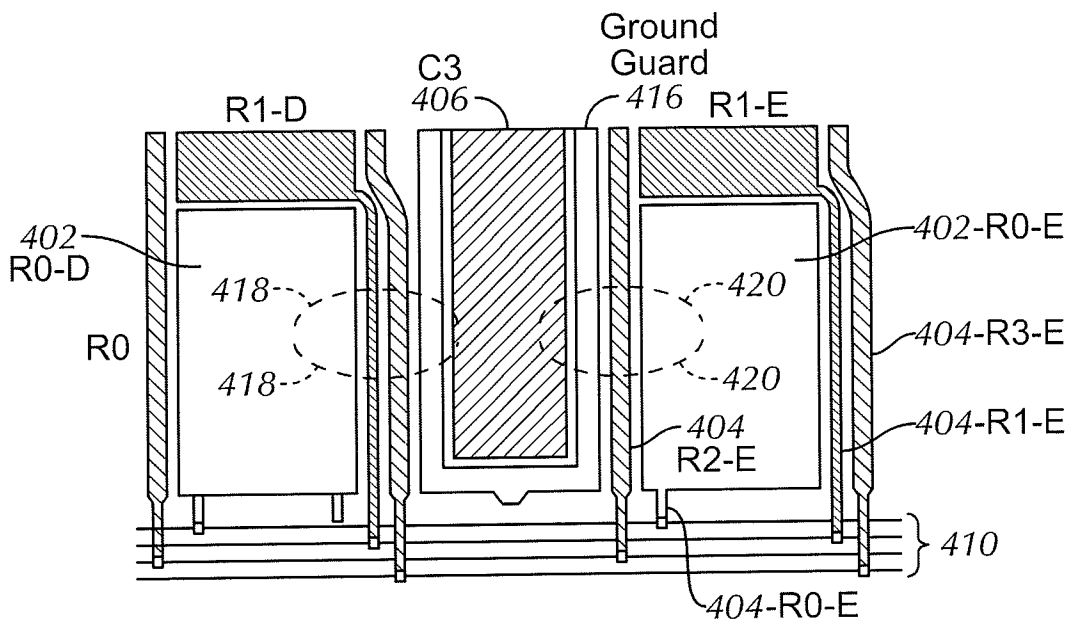
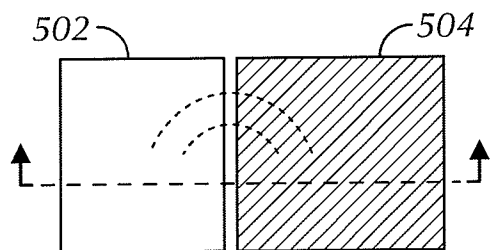
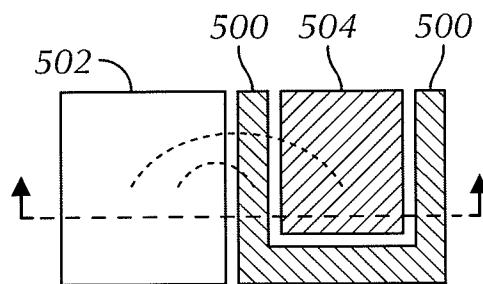


FIG. 4B

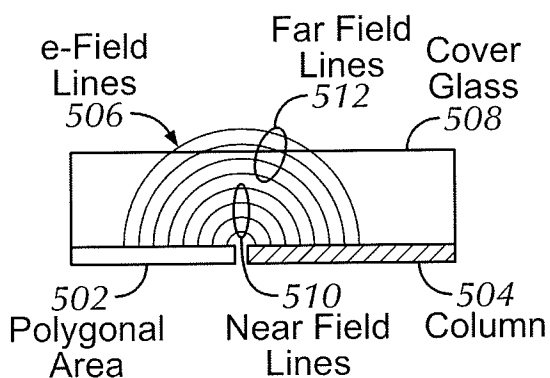
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Top View

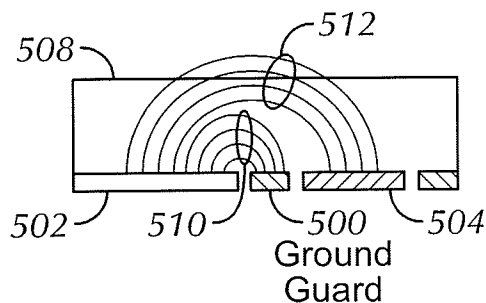


Top View



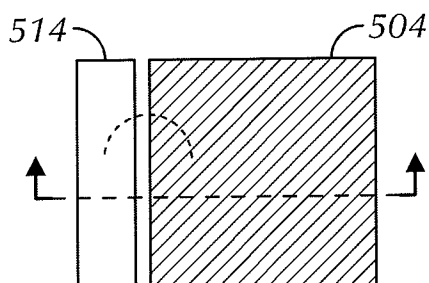
Side View

FIG. 5A

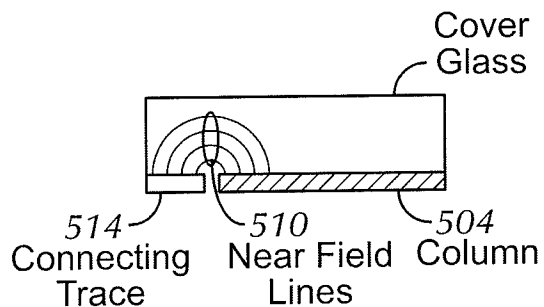


Side View

FIG. 5B

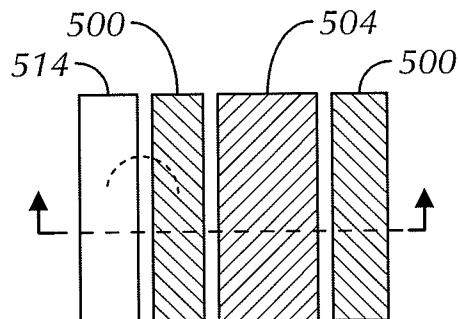


Top View

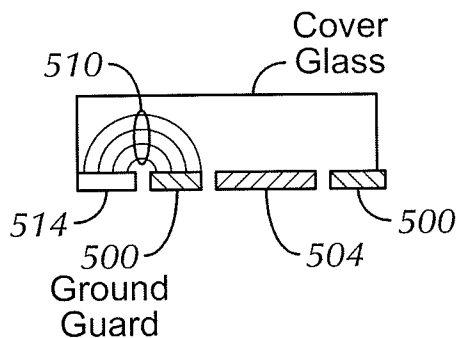


Side View

FIG. 5C

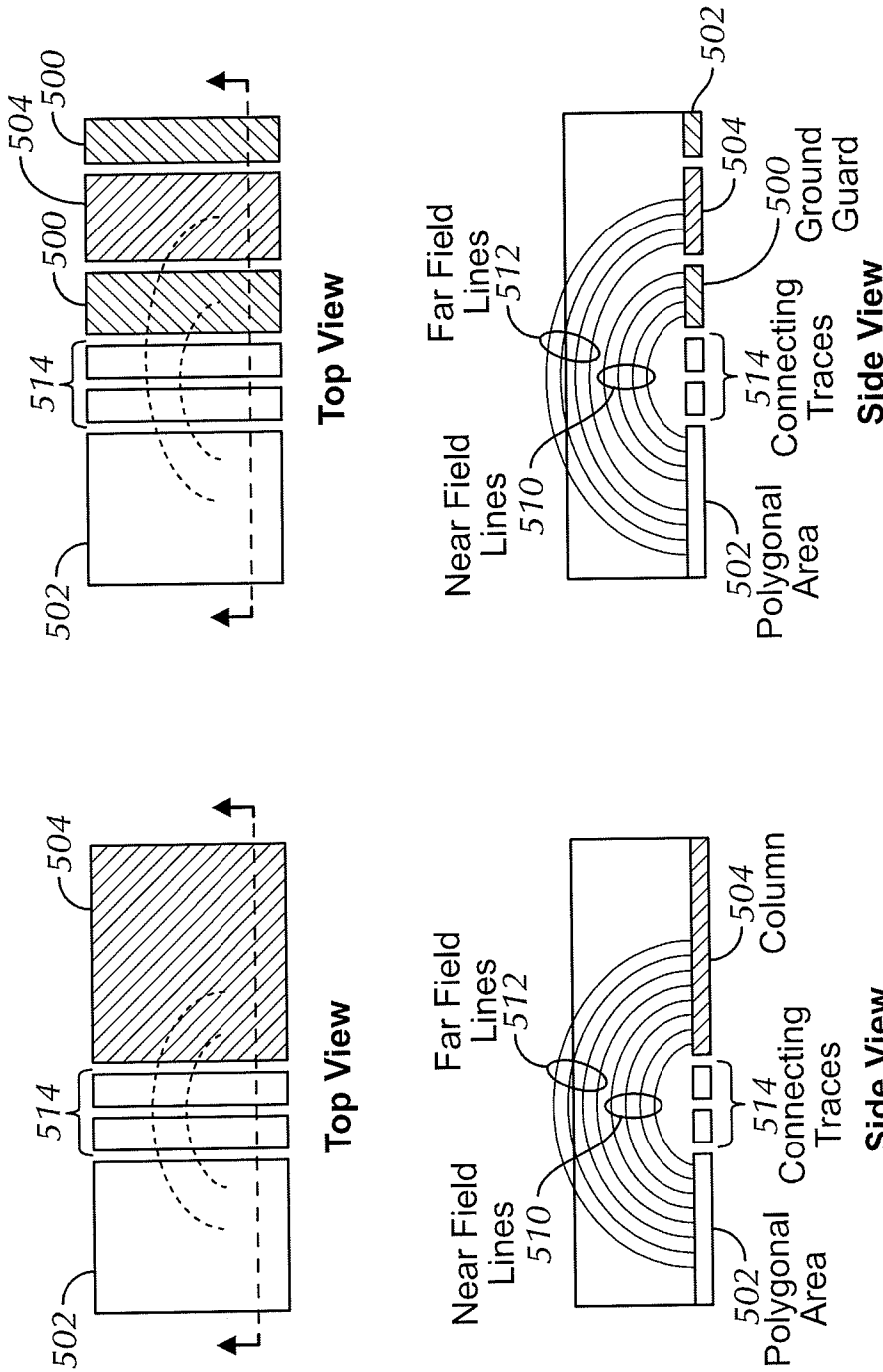


Top View



Side View

FIG. 5D



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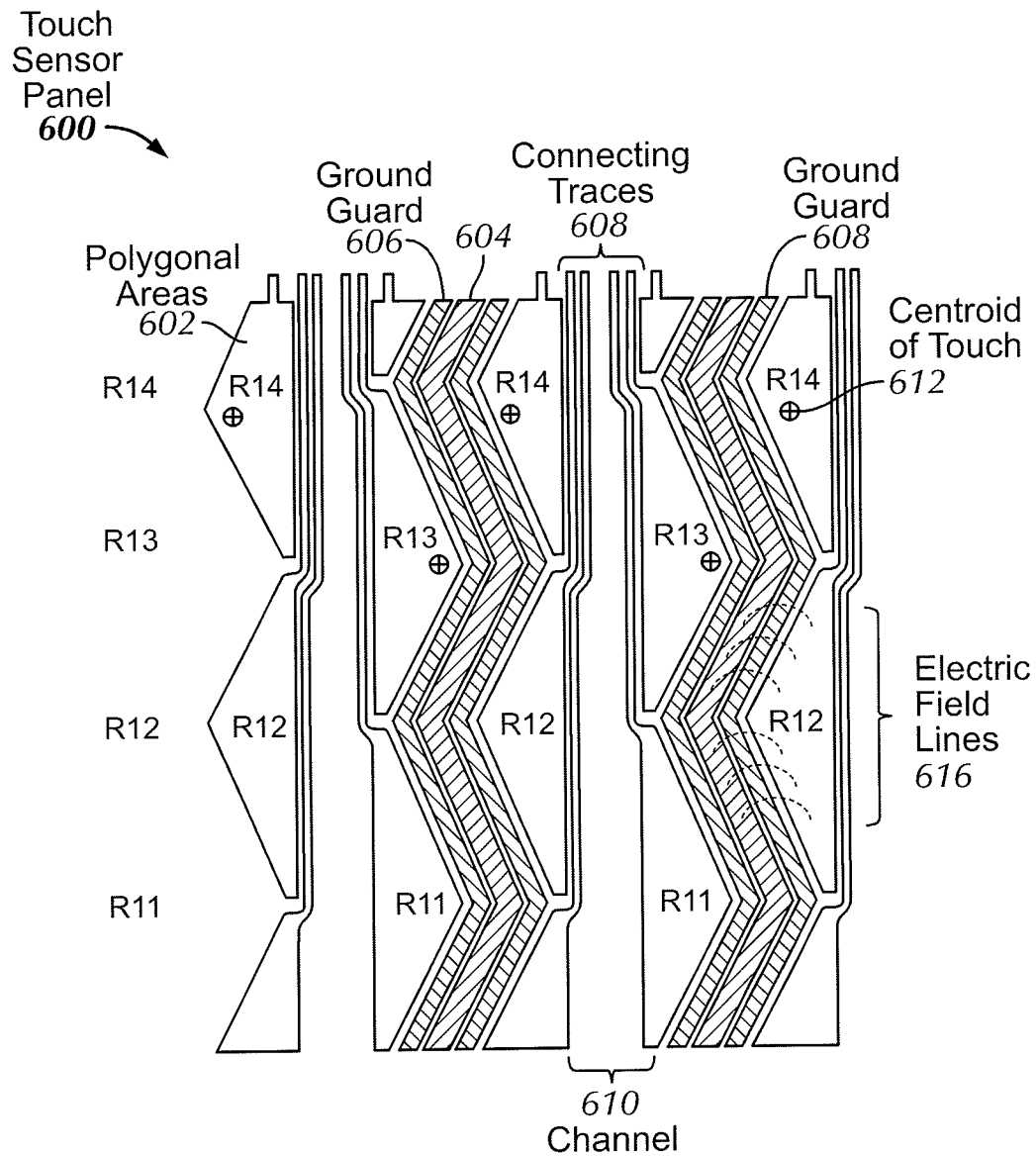


FIG. 6

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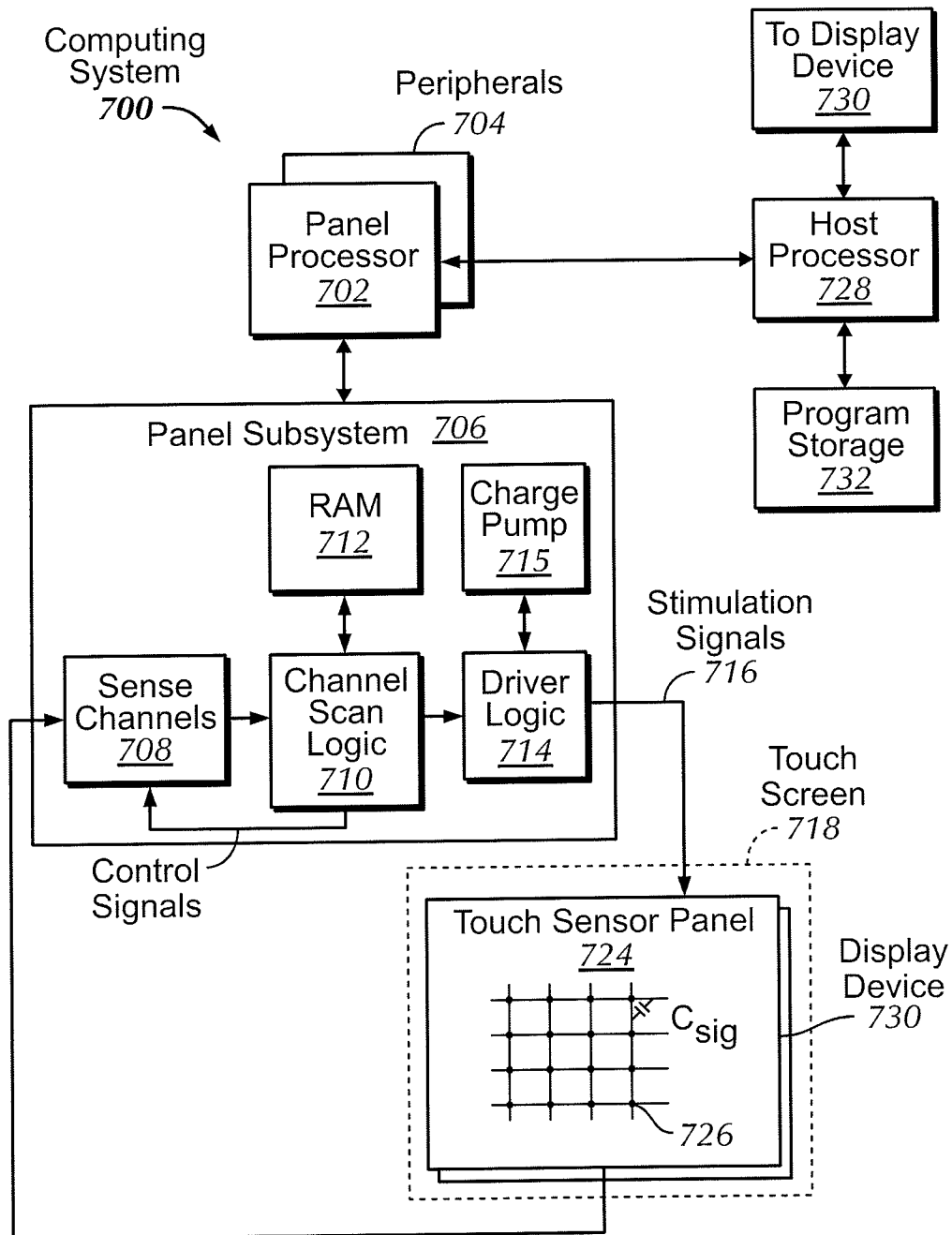


FIG. 7

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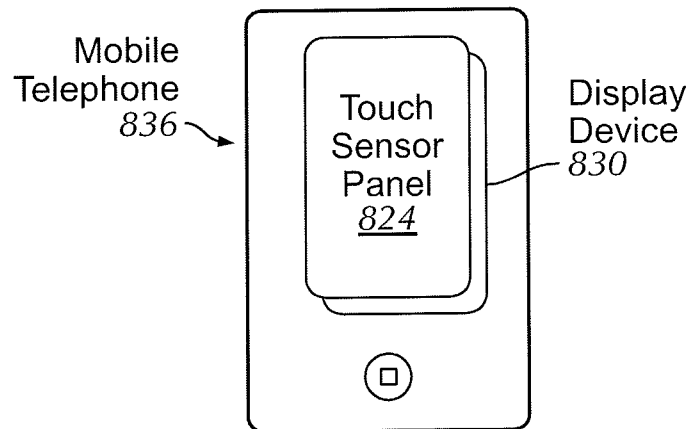


FIG. 8A

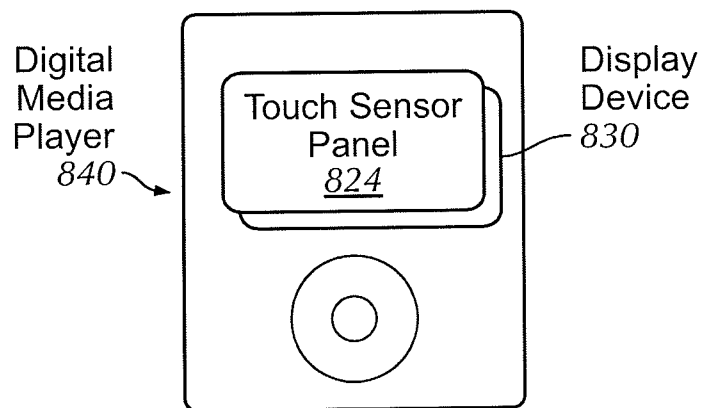


FIG. 8B

INTERNATIONAL SEARCH REPORT

International application No
PCT/US2009/041460

A. CLASSIFICATION OF SUBJECT MATTER
INV. G06F3/044

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)
G06F

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practical, search terms used)

EPO-Internal, WPI Data, INSPEC, COMPENDEX, IBM-TDB

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X	US 2008/074398 A1 (WRIGHT DAVID GORDON [US]) 27 March 2008 (2008-03-27) paragraphs [0028], [0035] - [0039], [0059] -----	1-29

☐ Further documents are listed in the continuation of Box C.

☒ See patent family annex.

* Special categories of cited documents :

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- *O* document referring to an oral disclosure, use, exhibition or other means
- *P* document published prior to the international filing date but later than the priority date claimed

- *T* later document published after the international filing date or priority date and not in conflict with the application but cited to understand the principle or theory underlying the invention
- *X* document of particular relevance; the claimed invention cannot be considered novel or cannot be considered to involve an inventive step when the document is taken alone
- *Y* document of particular relevance; the claimed invention cannot be considered to involve an inventive step when the document is combined with one or more other such documents, such combination being obvious to a person skilled in the art.
- * & * document member of the same patent family

Date of the actual completion of the international search

7 July 2009

Date of mailing of the international search report

17/07/2009

Name and mailing address of the ISA/

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NL - 2280 HV Rijswijk
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Authorized officer

Wiedmeyer, Vera

Information on patent family members

PCT/US2009/041460

Patent document
cited in search report

Publication
date:

Patent family member(s)

Publication
date

US 2008074398	A1	27-03-2008	NONE
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